

**Amendments to the Specification:**

Please replace the paragraph on page 10 starting at line 7 with the following amended paragraph:

In the case of the mold 10 shown in the drawing, the molding layer 11 has the same thickness in both rib non-formation portion 18 and the rib formation portion 16 (planar portion 11b). However, the thickness of the planar portion 11b of the molding layer 11 may be either smaller or greater than the thickness of the molding layer 11a of the rib formation portion 16, whenever necessary. Preferably, the thickness of the molding layer 11a of the rib non-formation portion 18 is smaller by a depth  $d$  than the thickness of the rib formation portion 16, ~~though it is not shown in the drawings.~~ Here, the depth  $d$  can be arbitrarily changed in accordance with the thickness of the rib pattern layer of the rib non-formation region of the PDP back surface plate to be produced, but is generally at least about  $5\text{ }\mu\text{m}$ , preferably from about  $5$  to  $20\text{ }\mu\text{m}$  and is further preferably within the range of from about  $10$  to about  $15\text{ }\mu\text{m}$ . According to this construction of the molding layer 11, when the thin film is formed in the rib non-formation region of the resulting back surface plate, the invention can acquire two effects, that is, protection of the electrodes and saving of the rib material. As to the electrodes not requiring protection, the effect of the invention can be exhibited when the thickness of the resulting thin film is so controlled as to approach zero.